

N-CHANNEL 30V - 0.008Ω - 11A SO-8 LOW GATE CHARGE STripFET™ II POWER MOSFET

TYPE	V_{DSS}	R _{DS(on)}	Ι _D
STS11NF3LL	30 V	< 0.011 Ω	11 A

- TYPICAL $R_{DS}(on) = 0.011\Omega @ 4.5V$
- OPTIMAL R_{DS(on)} Q_g TRADE-OFF @4.5V
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

DESCRIPTION

This application specific Power MOSFET is the third genaration of STMicroelectronics unique "Single Feature Size" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. When used as high and low side in buck regulators, it gives the best performance in terms of both conduction and switching losses. This is extremely important for motherboards where fast switching and high efficiency are of paramount importance.

APPLICATIONS

 SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY CPU CORE DC/DC CONVERTERS FOR MOBILE PCs

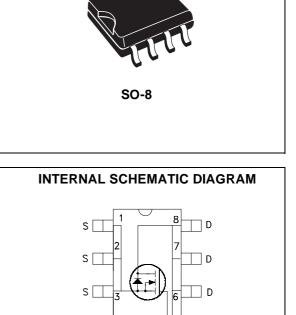
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	30	V
V _{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	30	V
V _{GS}	Gate- source Voltage	± 16	V
I _D	Drain Current (continuos) at $T_C = 25^{\circ}C$ (*) Drain Current (continuos) at $T_C = 100^{\circ}C$	11 7	A A
$I_{DM}(ullet)$	Drain Current (pulsed)	44	A
P _{TOT}	Total Dissipation at T _C = 25°C	2.5	W

(•) Pulse width limited by safe operating area

(*)Value limited by wires bonding

GΓ



D

5 sc12830

THERMAL I	ΔΤΑ		
Rthj-amb	Thermal Resistance Junction-ambient Max (#)	50	°C/W
Тј	Max. Operating Junction Temperature	150	°C
T _{stg}	Storage Temperature	–65 to 150	°C

(#) When Mounted on a 1inch² pad

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0$	30			V
I _{DSS}	Zero Gate Voltage	V _{DS} = Max Rating			1	μA
	Drain Current ($V_{GS} = 0$)	V_{DS} = Max Rating, T_{C} = 125 °C			10	μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	$V_{GS} = \pm 16V$			±100	nA

ON (1)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1			V
R _{DS(on)}	Static Drain-source On	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$		0.008	0.011	Ω
	Resistance	V_{GS} = 4.5 V, I _D = 5.5 A		0.011	0.013	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (1)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max,}$ $I_{D} = 5.5 \text{ A}$		15		S
Ciss	Input Capacitance	$V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0$		1700		pF
Coss	Output Capacitance			505		pF
C _{rss}	Reverse Transfer Capacitance			115		pF

ELECTRICAL CHARACTERISTICS (CONTINUED)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on Delay Time	V _{DD} = 15 V, I _D = 5.5 A		20		ns
t _r	Rise Time	$\label{eq:RG} \begin{array}{l} R_{G} = 4.7 \Omega \; V_{GS} = 4.5 \; V \\ (Resistive Load, see Fig. 3) \end{array}$		70		ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 15 \text{ V}, I_D = 11 \text{ A},$ $V_{GS} = 4.5 \text{ V}$		21 9.5 10	28	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off-Delay Time Fall Time	$\label{eq:VDD} \begin{array}{l} V_{DD} = 15 \mbox{ V, } I_D = 5.5 \mbox{ A,} \\ R_G = 4.7 \Omega, \mbox{ V}_{GS} = 4.5 \mbox{ V} \\ (\mbox{Resistive Load see, Fig. 3}) \end{array}$		40 20		ns ns

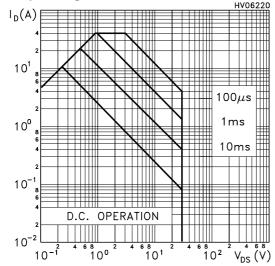
SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain Current				11	А
I _{SDM} (1)	Source-drain Current (pulsed)				44	А
V _{SD} (2)	Forward On Voltage	I _{SD} = 11 A, V _{GS} = 0			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery ChargeReverse Recovery Current	$I_{SD} = 11 \text{ A}, \text{ di/dt} = 100 \text{A/}\mu\text{s},$ $V_{DD} = 20 \text{ V}, \text{ T}_{\text{j}} = 150 ^{\circ}\text{C}$ (see test circuit, Figure 5)		45 52 2.3		ns nC A

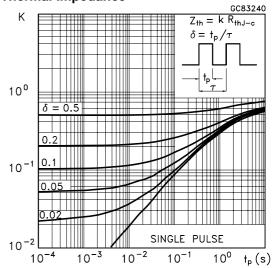
Note: 1. Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %.2. Pulse width limited by safe operating area.

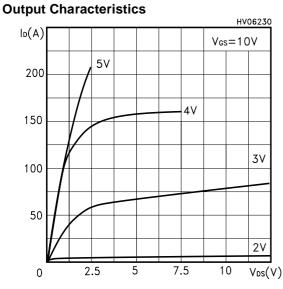
2. Fulse width inflited by sale operating a

Safe Operating Area

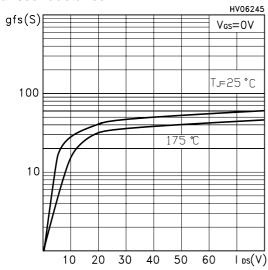


Thermal Impedance

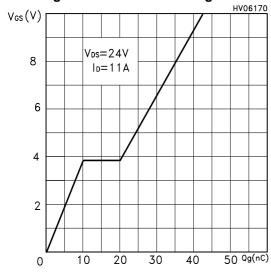




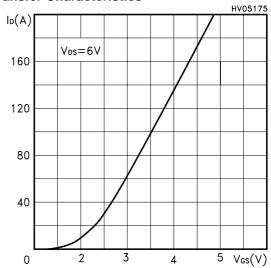
Transconductance



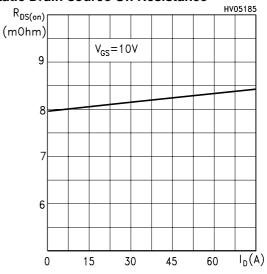
Gate Charge vs Gate-source Voltage



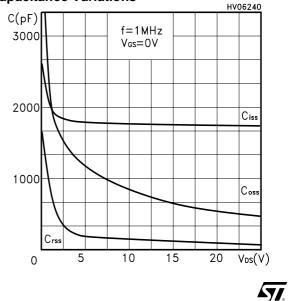
Transfer Characteristics

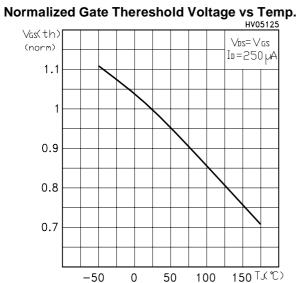


Static Drain-source On Resistance

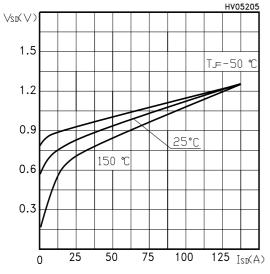


Capacitance Variations









Normalized On Resistance vs Temperature

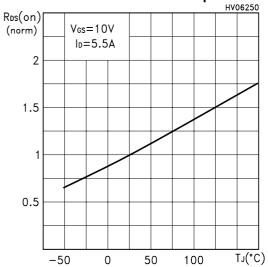


Fig. 1: Unclamped Inductive Load Test Circuit

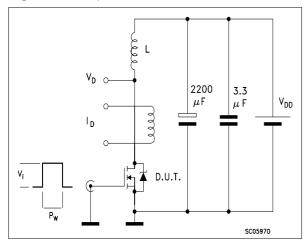


Fig. 3: Switching Times Test Circuit For Resistive Load

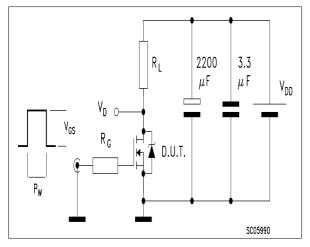


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

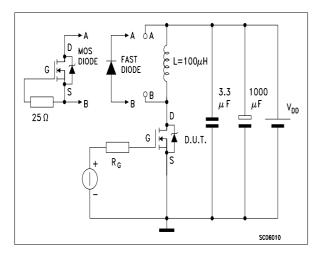


Fig. 2: Unclamped Inductive Waveform

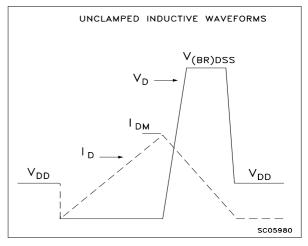
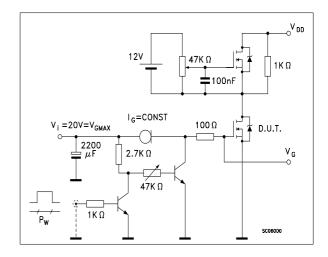


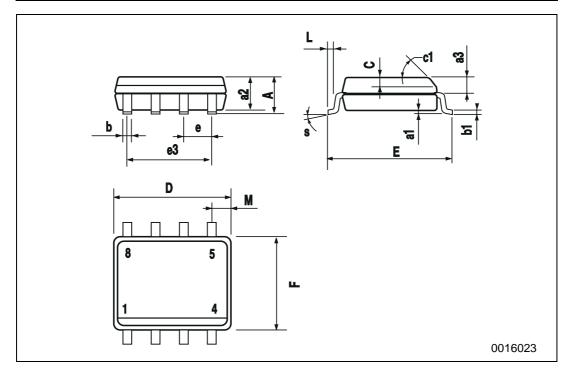
Fig. 4: Gate Charge test Circuit



57.

DIM.		mm		inch			
Dini.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А			1.75			0.068	
a1	0.1		0.25	0.003		0.009	
a2			1.65			0.064	
a3	0.65		0.85	0.025		0.033	
b	0.35		0.48	0.013		0.018	
b1	0.19		0.25	0.007		0.010	
С	0.25		0.5	0.010		0.019	
c1			45	(typ.)			
D	4.8		5.0	0.188		0.196	
E	5.8		6.2	0.228		0.244	
е		1.27			0.050		
e3		3.81			0.150		
F	3.8		4.0	0.14		0.157	
L	0.4		1.27	0.015		0.050	
М			0.6			0.023	

SO-8 MECHANICAL DATA



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specification mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics. The ST logo is a trademark of STMicroelectronics

© 2001 STMicroelectronics – Printed in Italy – All Rights Reserved STMicroelectronics GROUP OF COMPANIES Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia - Malta - Morocco -Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

http://www.st.com
